

## IN – Information Note

<b>Topic:</b>	<b>Bonding material change for u-blox M8 chip family</b>
	UBX-14037219
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### 1 Affected Products

Product Name	Order Number	Type No	Remarks
UBX-M8030-KT	UBX-M8030-KT		

### 2 Type of Change

- Hardware modification
- Firmware update
- Documentation update
- Others, Change of bonding material

### 3 Description of Change

The wire bonding material on u-blox M8 chip products will be changed from copper to gold.

### 4 Schedule

The change will affect the following u-blox M8 chip product variants as follows:

- UBX-M8030-KT
  - The product will remain in IP status. Products with the final bonding material will be available and shipped from the end of September 2014 onwards.
  - Mass production (and completion of qualification) originally planned for September 2014 is rescheduled for mid-January 2015.

### 5 Customer Impact and Recommended Action

UBX-M8030-KT with gold bonding is available from end of September 2014. It is recommended to use only this material for reliability stress tests in customer products.

Customers ordering UBX-M8030-KT in IP, will from End of September receive new material with gold bonding. u-blox will control inventory to secure this.

Current available UBX-M8030-KT chips are suitable for design-in, performance and design verification, and limited production lots.